Linux Interface board for TOF

Revision History

Revision: A  K. Weiner
Initial release
Board Details
1. Board Size: 2200mils x 1200mils
2. Board Thickness: 62mils
3. Component count: 27
4. Pad Count: 122
5. Hole Count: 88
6. Soldermask Color: Green
7. Silkscreen Color: White
8. No Silkscreen over exposed copper.
9. Dimensions shown are in mils.
10. Boards Shall be fabricated to IPC-600 Class 1
11. The board Material shall be: FR-4
12. The PCB assembly shall be ROHS compliant.
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### Layers Currently On

<table>
<thead>
<tr>
<th>Title Block</th>
<th>Board Outline</th>
<th>Multi-Layer</th>
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<tbody>
<tr>
<td>Title</td>
<td>Number</td>
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<td>TOF Linux Interface Board</td>
<td>EVM-TOFDEMO-04</td>
<td>Mid1 Layer - GND</td>
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<td>Rev</td>
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Variant: [No Variations]  Print Date: 14.01.2019
File: PCBпубликация  Drawn By: Z.00k
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Layers Currently On

Title Block
Board Outline
Multi-Layer

Title       TOF Linux Interface Board
Number      EVM-TOFDEMO-04
Print Name   Mid2 Layer - PWR
Variant: [No Variations]
Print Date: 14.01.2019
File: PCB.PcbDoc
Drawn By: [2004c]
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Layers Currently On

Title Block
Drill Drawing
Board Outline

Title: TOF Linux Interface Board
Number: EVM-TOFDEMO-04
Rev: A
Print Name: Drill Drawing
Variant: [No Variations]
Print Date: 14.01.2019
File: PCB.PĆbozz
Drawn By: [2.20A]
Board Details

1. Board Size: 2200mils x 1200mils
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Layers Currently On

Title Block
Board Outline
Assembly Bottom
Multi-Layer

Title: TOF Linux Interface Board
Number: EVM-TOFDEMO-04
Rev: A
Print Name: BOTTOM Assembly Mirrored
Variant: Default Build
Print Date: 14.01.2019
File: PCB_PcbDoc
Drawn By: J. Doe
Design Rules Verification Report
Filename : \fsup04\cnc_prodmgmt\OSL\11_HW_Application_PS\Koloth\Hardware\EVM-TOFD

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## Electrical Rules Check Report

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Montag 14 Jän 2019   10:52:22 AM
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<td>CONN FFC TOP 14POS 0.50MM R/A</td>
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